



N.241DV1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Farrar et al.
Appl. No. : 10/662,828
Filed : September 15, 2003
For : MULTIPLE CHIP STACK
STRUCTURE AND COOLING
SYSTEM
Examiner : Bradley Smith
Group Art Unit : 2824

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

September 28, 2004

(Date)

Linda H. Liu, Reg. No. 51,240

RESPONSE TO OFFICE ACTION MAILED JUNE 29, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed June 29, 2004, the Applicant respectfully submits the amendments and remarks as indicated below.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Remarks/Arguments begin on page 7 of this paper.